

## 2A, 100V - 200V Surface Mount Ultra Fast Rectifier

#### **FEATURES**

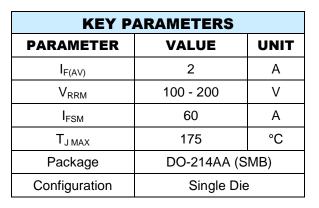
- Glass passivated junction chip
- Ideal for automated placement
- Low profile package
- Ultra fast recovery time for high efficiency
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

#### **APPLICATIONS**

- Switching mode power supply (SMPS)
- Adapters
- Lighting application
- Converter

#### **MECHANICAL DATA**

- Case: DO-214AA (SMB)
- Molding compound meets UL 94V-0 flammability rating
- Part no. with suffix "H" means AEC-Q101 qualified
- Packing code with suffix "G" means green compound (halogen-free)
- Moisture sensitivity level: level 1, per J-STD-020
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: As marked
- Weight: 0.09 g (approximately)







DO-214AA (SMB)

PARAMETER	SYMBOL	ESH2B	ESH2C	ESH2D	UNIT
Marking code on the device		ESH2B	ESH2C	ESH2D	
Repetitive peak reverse voltage	$V_{RRM}$	100	150	200	V
Reverse voltage, total rms value	$V_{R(RMS)}$	70	105	140	V
Maximum DC blocking voltage	$V_{DC}$	100	150	200	V
Forward current	I <sub>F(AV)</sub>	2		Α	
Surge peak forward current, 8.3 ms single half sine-wave superimposed on rated load per diode	I <sub>FSM</sub>	60		А	
Junction temperature	TJ	- 55 to +175		°C	
Storage temperature	T <sub>STG</sub>	- 55 to +175		°C	



# **ESH2B - ESH2D**Taiwan Semiconductor

THERMAL PERFORMANCE						
PARAMETER	SYMBOL	LIMIT	UNIT			
Junction-to-lead thermal resistance	$R_{\Theta JL}$	20	°C/W			
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	75	°C/W			

ELECTRICAL SPECIFICATIONS (T <sub>A</sub> = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage per diode (1)	I <sub>F</sub> = 2A,T <sub>J</sub> = 25°C	V <sub>F</sub>	-	0.9	V
Decree 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2	T <sub>J</sub> = 25°C	I <sub>R</sub>	-	2	μA
Reverse current @ rated V <sub>R</sub> per diode (2)	T <sub>J</sub> = 125°C		-	50	μA
Junction capacitance	1 MHz, V <sub>R</sub> =4.0V	CJ	25	-	pF
Payarea recovery time	I <sub>F</sub> =0.5A ,I <sub>R</sub> =1.0A I <sub>RR</sub> =0.25A	t <sub>rr</sub>	-	20	ns
Reverse recovery time	I <sub>RR</sub> =0.25A				

### Notes:

- 1. Pulse test with PW=0.3 ms
- 2. Pulse test with PW=30 ms

ORDERING INFORMATION						
PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX(*)	PACKAGE	PACKING	
ESH2x (Note 1)		R5		SMB	850 / 7" Plastic reel	
	Н	R4	G	SMB	3,000 / 13" Paper reel	
		M4		SMB	3,000 / 13" Plastic reel	

#### Note:

- 1. "x" defines voltage from 100V (ESH2B) to 200V (ESH2D)
- \*: Optional available

EXAMPLE P/N					
EXAMPLE P/N	PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION
ESH2DHR5G	ESH2D	Н	R5	G	AEC-Q101 qualified Green compound



### **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

Fig.1 Forward Current Derating Curve

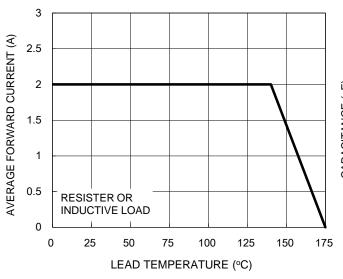


Fig.2 Typical Junction Capacitance

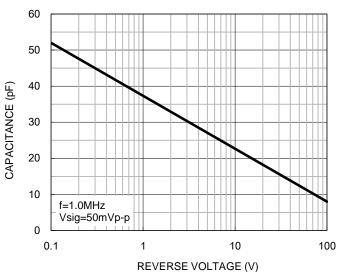


Fig.3 Typical Reverse Characteristics

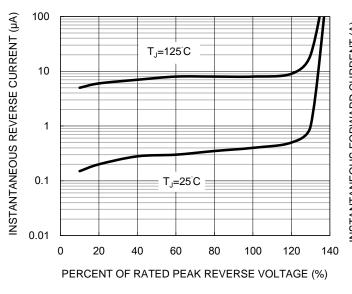
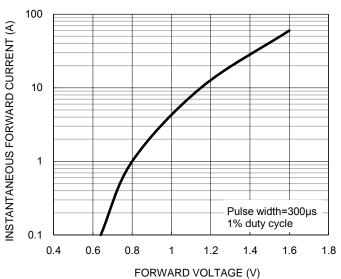


Fig.4 Typical Forward Characteristics



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### **CHARACTERISTICS CURVES**

(T<sub>A</sub> = 25°C unless otherwise noted)

Fig.5 Maximum Non-repetitive Forward Surge Current

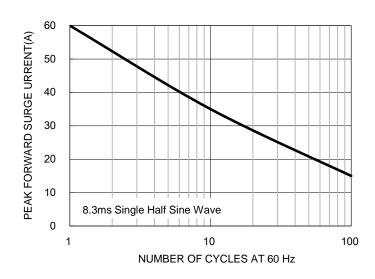
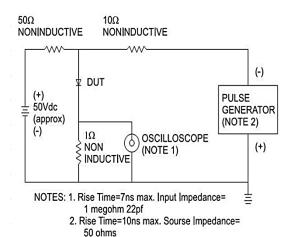
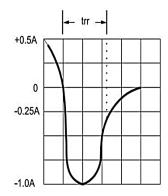


Fig.6 Reverse Recovery Time Characteristic And Test Circuit Diagram



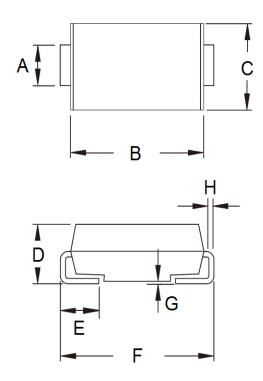






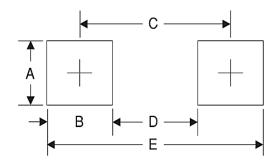
## **PACKAGE OUTLINE DIMENSIONS**

DO-214AA (SMB)



DIM.	Unit	(mm)	Unit (inch)		
DIIVI.	Min	Max	Min	Max	
А	1.95	2.20	0.077	0.087	
В	4.05	4.60	0.159	0.181	
С	3.30	3.95	0.130	0.156	
D	1.95	2.65	0.077	0.104	
Е	0.75	1.60	0.030	0.063	
F	5.10	5.60	0.201	0.220	
G	0.05	0.20	0.002	0.008	
Н	0.15	0.31	0.006	0.012	

## **SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)
A	2.3	0.091
В	2.5	0.098
С	4.3	0.169
D	1.8	0.071
E	6.8	0.268

### **MARKING DIAGRAM**



P/N = Marking Code = Green Compound G YW = Date Code = Factory Code



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